

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 20	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

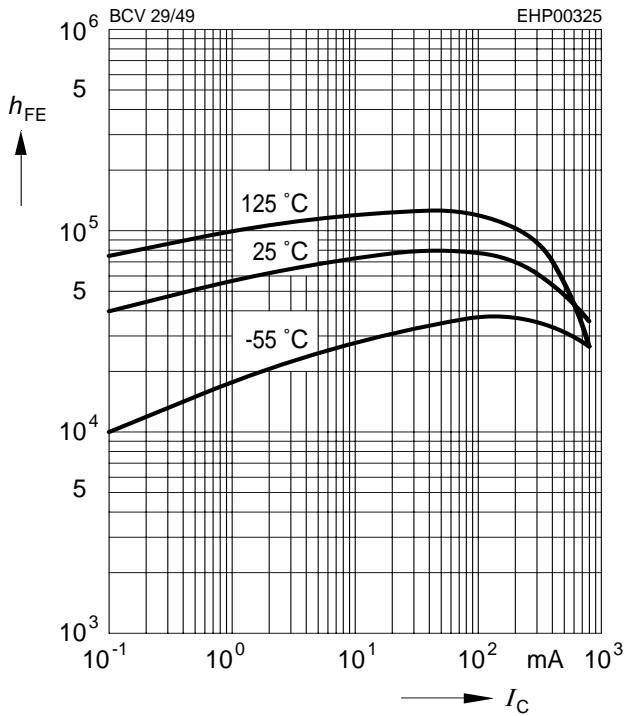
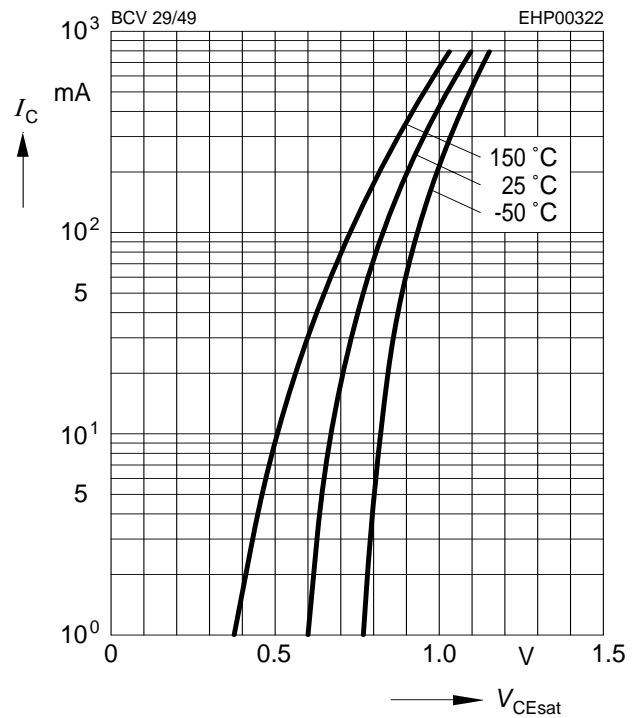
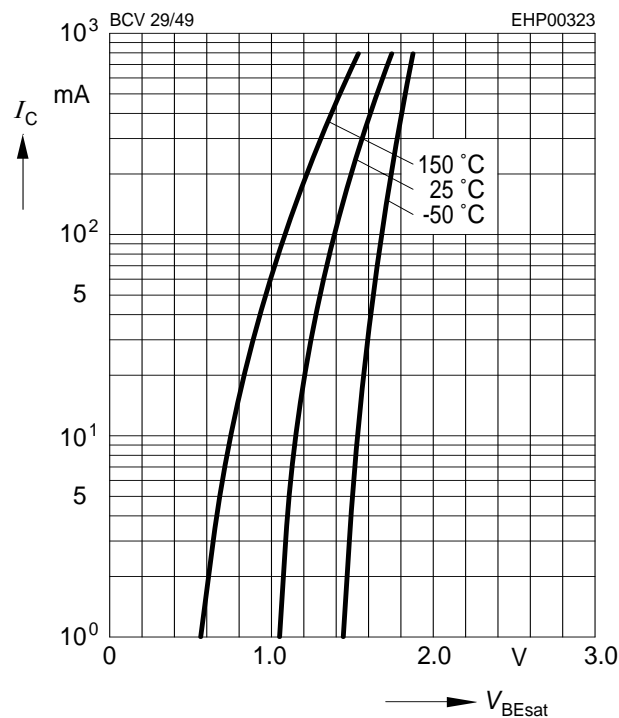
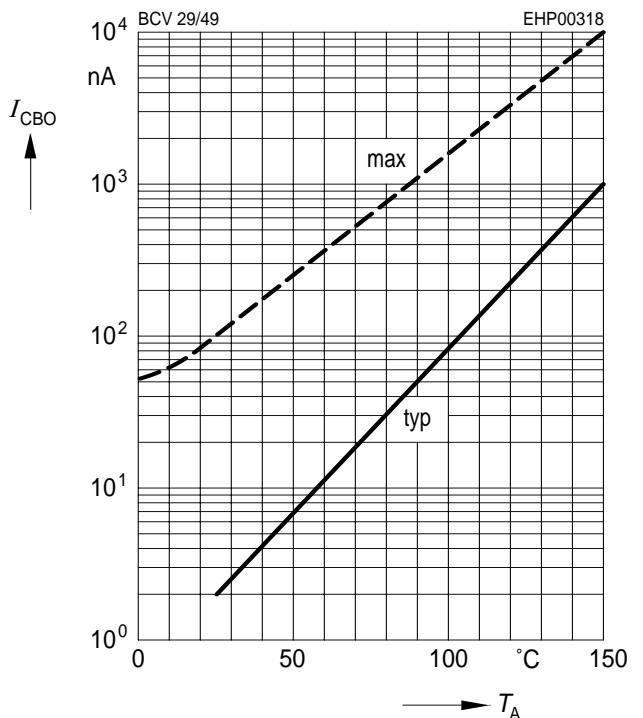
Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Collector-emitter breakdown voltage $I_C = 10\text{ mA}$, $I_B = 0$, BCV29 $I_C = 10\text{ mA}$, $I_B = 0$, BCV49	$V_{(BR)CEO}$	30 60	- -	- -	V
Collector-base breakdown voltage $I_C = 100\text{ }\mu\text{A}$, $I_E = 0$, BCV29 $I_C = 100\text{ }\mu\text{A}$, $I_E = 0$, BCV49	$V_{(BR)CBO}$	40 80	- -	- -	
Emitter-base breakdown voltage $I_E = 10\text{ }\mu\text{A}$, $I_C = 0$	$V_{(BR)EBO}$	10	-	-	
Collector-base cutoff current $V_{CB} = 30\text{ V}$, $I_E = 0$, BCV29 $V_{CB} = 60\text{ V}$, $I_E = 0$, BCV49 $V_{CB} = 30\text{ V}$, $I_E = 0$, $T_A = 150^\circ\text{C}$, BCV29 $V_{CB} = 60\text{ V}$, $I_E = 0$, $T_A = 150^\circ\text{C}$, BCV49	I_{CBO}	- - - -	- - - -	0.1 0.1 10 10	μA
Emitter-base cutoff current $V_{EB} = 4\text{ V}$, $I_C = 0$	I_{EBO}	-	-	100	nA
DC current gain ¹⁾ $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 1\text{ V}$, BCV29 $I_C = 100\text{ }\mu\text{A}$, $V_{CE} = 1\text{ V}$, BCV49 $I_C = 10\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 10\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV49 $I_C = 100\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 100\text{ mA}$, $V_{CE} = 5\text{ V}$, BCV49 $I_C = 0.5\text{ A}$, $V_{CE} = 5\text{ V}$, BCV29 $I_C = 0.5\text{ A}$, $V_{CE} = 5\text{ V}$, BCV49	h_{FE}	4000 2000 10000 4000 20000 10000 4000 2000	- - - - - - - -	- - - - - - - -	-
Collector-emitter saturation voltage ¹⁾ $I_C = 100\text{ mA}$, $I_B = 0.1\text{ mA}$	V_{CEsat}	-	-	1	V
Base emitter saturation voltage ¹⁾ $I_C = 100\text{ mA}$, $I_B = 0.1\text{ mA}$	V_{BEsat}	-	-	1.5	

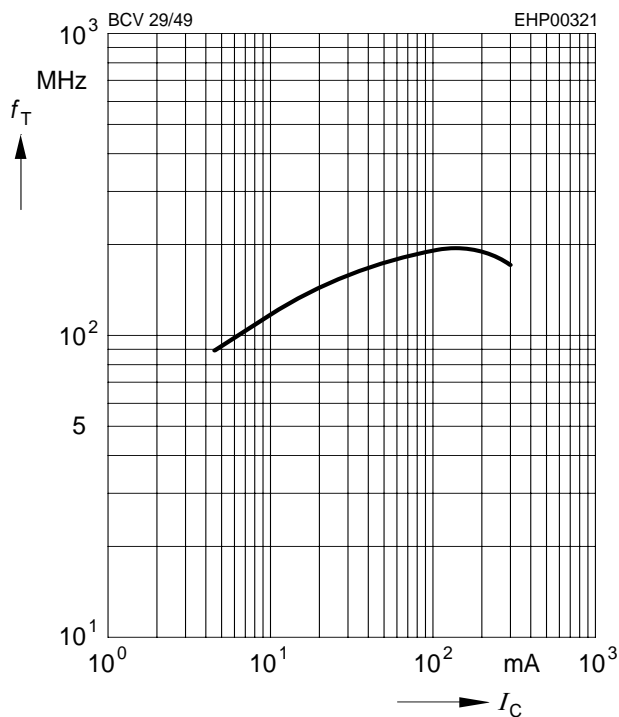
¹Pulse test: $t < 300\mu\text{s}$; $D < 2\%$
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Transition frequency $I_C = 50\text{ mA}$, $V_{CE} = 5\text{ V}$, $f = 100\text{ MHz}$	f_T	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10\text{ V}$, $f = 1\text{ MHz}$	C_{cb}	-	3	-	pF

DC current gain $h_{FE} = f(I_C)$
 $V_{CE} = 5 \text{ V}$

Collector-emitter saturation voltage
 $I_C = f(V_{CEsat}), h_{FE} = 1000$

Base-emitter saturation voltage
 $I_C = f(V_{BEsat}), h_{FE} = 1000$

Collector cutoff current $I_{CBO} = f(T_A)$
 $V_{CB} = V_{CEmax}$


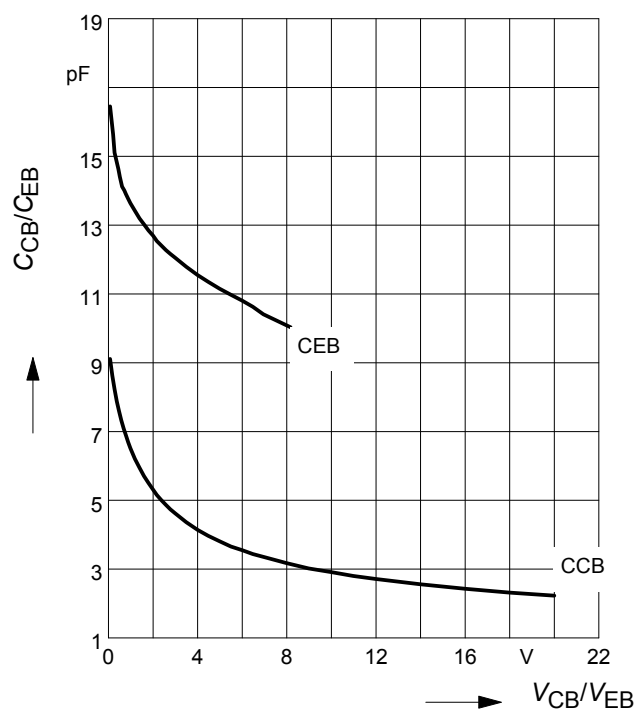
Transition frequency $f_T = f(I_C)$

$V_{CE} = 5\text{ V}$

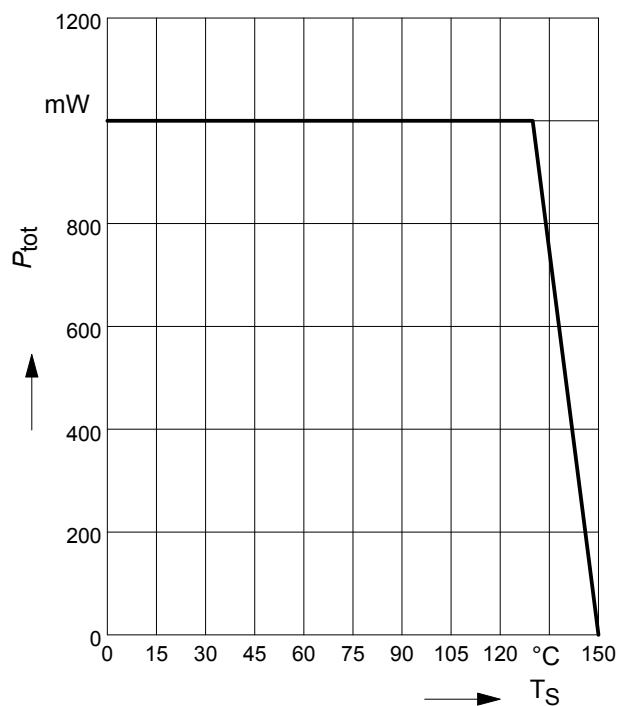


Collector-base capacitance $C_{cb} = f(V_{CB})$

Emitter-base capacitance $C_{eb} = f(V_{EB})$

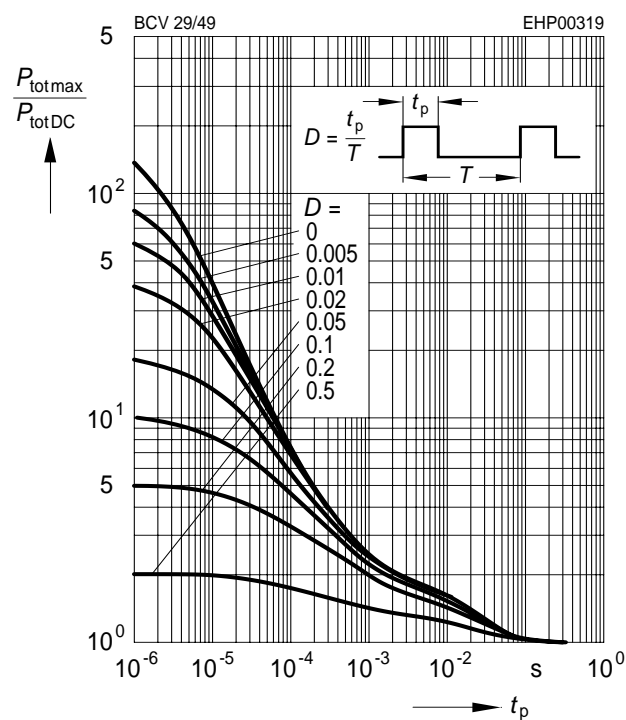


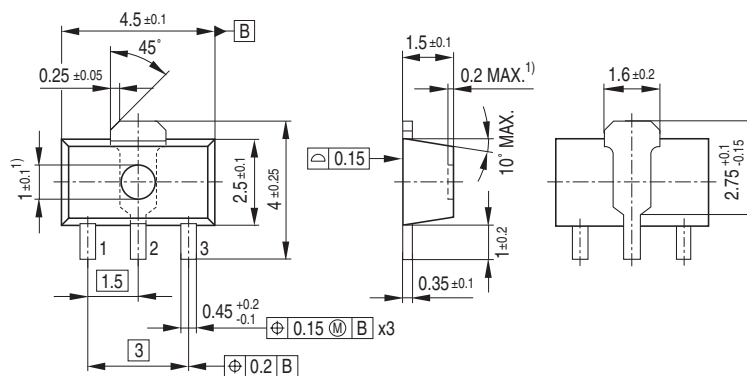
Total power dissipation $P_{tot} = f(T_S)$



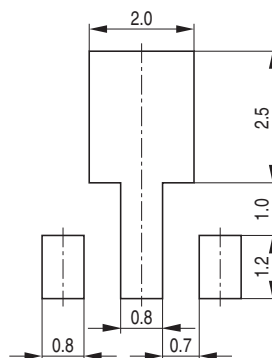
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$





Foot Print



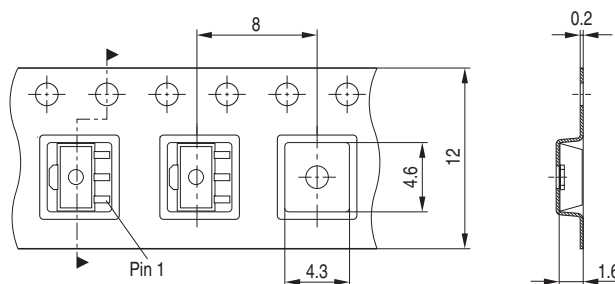
BAW78D
Type code

Pin 1

2005, June
Date code (YM)

Infineon
Manufacturer

Reel ø180 mm = 1.000 Pieces/Reel
Reel ø330 mm = 4.000 Pieces/Reel



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